

Material Composition Data



Product: GXO-2201

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GXO-2201 - 1.8 ~ 3.3V CMOS Oscillator

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
Adhesive	Epoxy Resin	Ag	7440-22-4	0.079	71.82
	Epoxy Resin	Amide	461-58-5	0.001	0.91
	Epoxy Resin	Epoxy resin A type	25068-38-6	0.009	8.18
	Epoxy Resin	Epoxy resin F type	28064-14-4	0.010	9.09
	Epoxy Resin	Imidazole	827-43-0	0.001	0.91
	Epoxy Resin	Modified Epoxy Resin	9003-36-5	0.010	9.09
Au Wire	Metal	Au	7440-57-5	0.026	100.00
Base	Ceramic	Ag	7440-22-4	0.320	4.51
	Ceramic	Al2O3	1344-28-1	4.607	64.89
	Ceramic	Au	7440-57-5	0.060	0.85
	Ceramic	Co	7440-48-4	0.170	2.39
	Ceramic	Cu	7440-50-8	0.060	0.85
	Ceramic	Fe	7439-89-6	0.400	5.63
	Ceramic	MgO	1309-48-4	0.010	0.14
	Ceramic	Mn2O3	1317-34-6	0.170	2.39
	Ceramic	Mo	7439-98-7	0.731	10.30
	Ceramic	MoO3	1313-27-5	0.020	0.28
	Ceramic	Ni	7440-02-0	0.391	5.51
	Ceramic	SiO2	14808-60-7	0.161	2.27
	Blank	Quartz crystal	SiO2	14808-60-7	0.010
Electrode	Metal layer	Ag	7440-22-4	0.010	100.00
IC	IC	Si	7440-21-3	0.080	100.00
Lid	Kovar	Co	7440-48-4	0.247	16.30
	Kovar	Fe	7439-89-6	0.730	48.18
	Kovar	Mn	7439-96-5	0.007	0.46
	Kovar	Ni	7440-02-0	0.384	25.35
	Kovar	Si	7440-21-3	0.004	0.26
	Plating	Ni	7440-02-0	0.143	9.44
Silver Glue	Silicone resin	Ag	7440-22-4	0.008	72.73
	Silicone resin	C12H26	112-40-3	0.001	9.09
	Silicone resin	Si	7440-21-3	0.001	9.09
	Silicone resin	SiO2	14808-60-7	0.001	9.09

Total Mass: 8.862 mg

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